

S14 3	1	electro\$1magnetic with heating same inter\$1connect\$3 same (contactor contacting)	USPAT; EPO; JPO	OR	ON	2004/08/25 12:10
S14 4	65	electro\$1magnetic with heating same inter\$1connect\$3	USPAT; EPO; JPO	OR	ON	2004/08/25 12:10
S14 5	2	"4439284".pn.	USPAT; EPO; JPO	OR	ON	2004/08/25 16:09
S14 6	2421	heat\$3 near treat\$3 and spring same (contact pad land)	USPAT; EPO; JPO	OR	ON	2004/08/25 16:11
S14 7	63	heat\$3 near treat\$3 and spring same (contact pad land) and ferro\$1magnetic	USPAT; EPO; JPO	OR	ON	2004/08/25 16:16
S14 8	3937	heat\$3 near treat\$4 and (contact pad land) same (micro\$1electronic spring)	USPAT; EPO; JPO	OR	ON	2004/08/25 16:19
S14 9	108	(heat\$3 near treat\$4 and (contact pad land) same (micro\$1electronic spring)) and ferro\$1magnetic	USPAT; EPO; JPO	OR	ON	2004/08/25 16:16
S15 0	66	heat\$3 near treat\$4 same micro\$1electronic	USPAT; EPO; JPO	OR	ON	2004/08/25 16:20
S15 1	58	heat\$4 near3 treat\$4 with spring near3 contact	USPAT; EPO; JPO	OR	ON	2005/01/10 17:29
S15 2	16051	heat\$3 near2 treat\$4 with (spring contact wire micro\$1electronic)	USPAT; EPO; JPO	OR	ON	2005/01/11 10:19
S15 3	6817	heat\$3 near2 treat\$4 near4 (spring contact wire micro\$1electronic)	USPAT; EPO; JPO	OR	ON	2005/01/11 10:19
S15 4	1787	heat\$3 near2 treat\$4 near4 (spring contact wire micro\$1electronic) and (interpose substrate)	USPAT; EPO; JPO	OR	ON	2005/01/11 10:19
S15 5	789	heat\$3 near2 treat\$4 near4 (spring contact wire micro\$1electronic) and (interpose substrate) and coat\$3	USPAT; EPO; JPO	OR	ON	2005/01/11 10:21
S15 6	8	heat\$3 near2 treat\$4 near4 (spring contact wire micro\$1electronic) with interconnect\$3 and (interpose substrate) and coat\$3	USPAT; EPO; JPO	OR	ON	2005/01/11 10:22
S15 7	31	heat\$3 near2 treat\$4 near4 (spring contact wire micro\$1electronic) with interconnect\$3 and (interpose substrate)	USPAT; EPO; JPO	OR	ON	2005/01/11 10:22
S15 8	471	heat\$3 near2 treat\$4 near4 (spring contact wire micro\$1electronic) with (interpose substrate)	USPAT; EPO; JPO	OR	ON	2005/01/11 10:23
S15 9	80	heat\$3 near2 treat\$4 near4 (spring wire micro\$1electronic) with (interpose substrate)	USPAT; EPO; JPO	OR	ON	2005/01/11 10:43
S16 0	3946	heat\$3 near1 treat\$4 near4 (spring wire micro\$1electronic)	USPAT; EPO; JPO	OR	ON	2005/01/11 10:44

S16 1	64	heat\$3 near1 treat\$4 near4 (spring wire micro\$1electronic) and (ferromagnetic nickel\$1cobalt Ni\$1Co)	USPAT; EPO; JPO	OR	ON	2005/01/11 11:04
S16 2	115	("5476211").URPN.	USPAT	OR	ON	2005/01/11 11:01
S16 3	58	heat\$3 near1 treat\$4 near4 (wire micro\$1electronic) and (ferromagnetic nickel\$1cobalt Ni\$1Co)	USPAT; EPO; JPO	OR	ON	2005/01/11 11:05
S16 4	9	heat\$3 near1 treat\$4 near4 (wire spring) same (ferromagnetic nickel\$1cobalt Ni\$1Co)	USPAT; EPO; JPO	OR	ON	2005/01/11 11:05
S16 5	0	heat\$3 near1 treat\$4 near4 (wire spring) with plurality same (ferromagnetic nickel\$1cobalt Ni\$1Co)	USPAT; EPO; JPO	OR	ON	2005/01/11 11:05